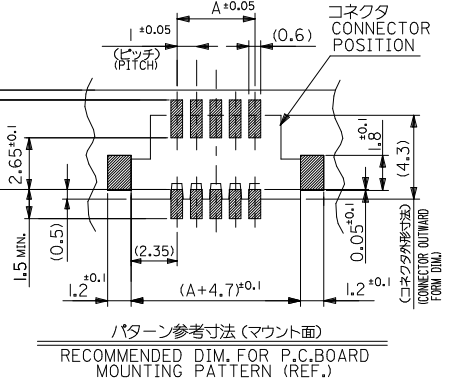
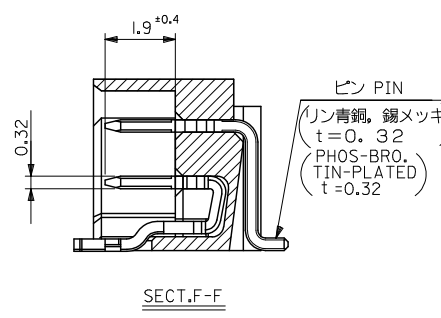
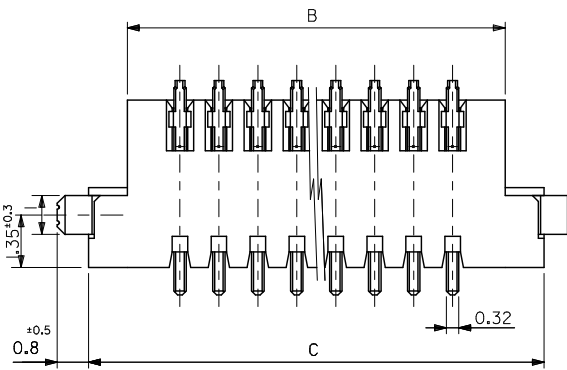
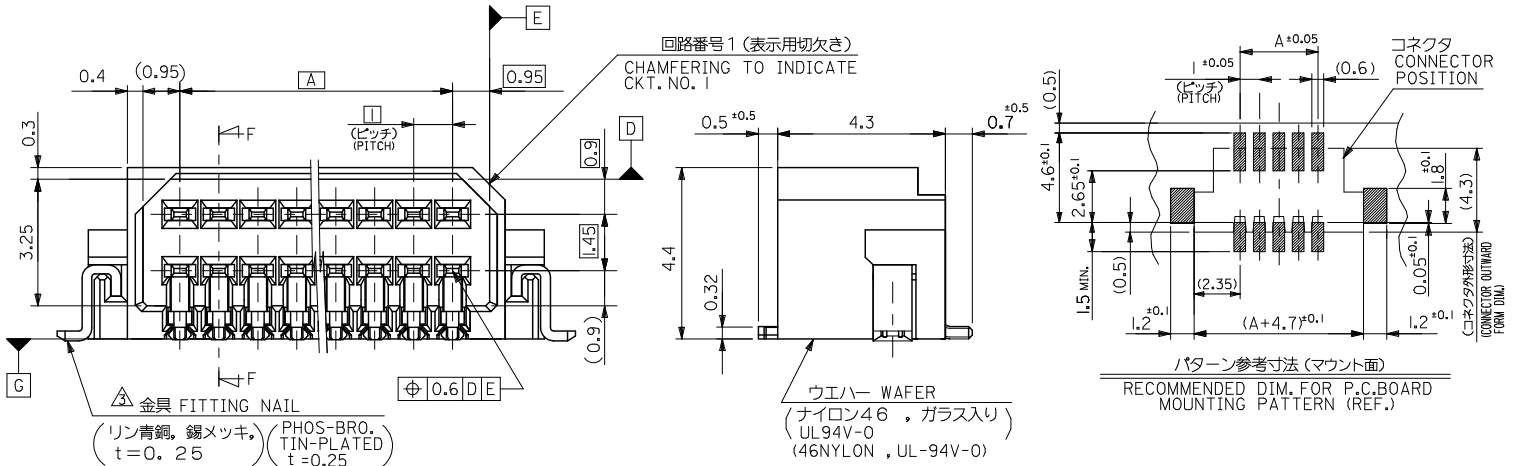


10 9 8 7 6 5 4 3 2 1



18.7	16.7	14	53268-3020	30
15.7	13.7	11	53268-2420	24
12.7	10.7	8	53268-1820	18
6.7	4.7	2	53268-0620	6
C	B	A	MATERIAL NO.	種数 (CIRCUIT)

注記 NOTES.

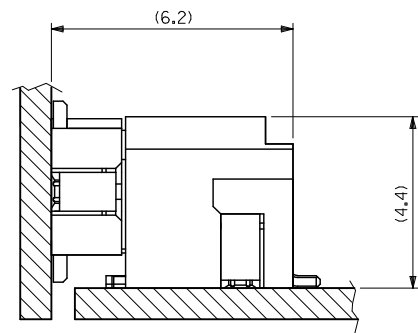
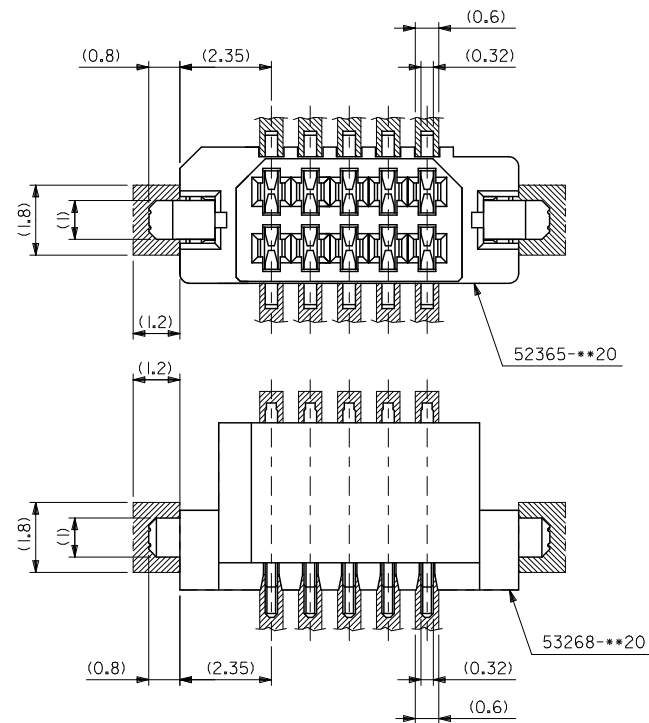
1. 嵌合相手 : 52365-***10 , 52365-***20
MATES WITH : 52365-***10 , 52365-***20
2. ハウジングの底面 G からの金具及びターミナル半田付面のズレ量は上方0.1MAX. 下方0.15MAX. とする。
MISALIGNMENT OF SOLDER TAIL TIP AND FITTING NAIL FROM G
: UPPER DIRECTION 0.1mmMAX.
: LOWER DIRECTION 0.15mmMAX.

△ パターンハクリ止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

REVISED EC NO: J2009-0666 DRAWN: KANAKURA 2008/09/25 CHKD: HARUYAMA 2008/09/25 APPR: NIKITA 2008/09/25 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. ENOMOTO	DATE '92/8/4	DOCUMENT NO. SD-53268-011		
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2	

ib_frame_A3_J_ME_S
Rev. E 2006/04/15

EN-02JA(021)



基板取付推奨レイアウト
RECOMMENDED P.C.BOARD LAYOUT

MODEL NO. 53268-***20

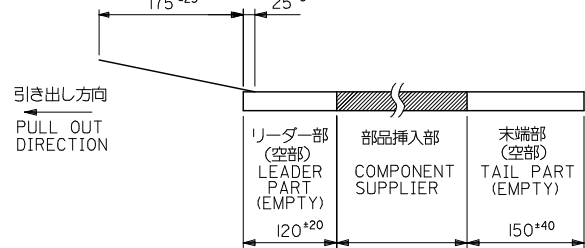
REVISED IEC NO: J2009-0666 DRAWN: DRWNAKURAA 2008/09/25 CHECKED: CHYKDI HARUYAMA 2008/09/25 APPROVED: APPRNIKIITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)	
	10 OVER 30 UNDER	± ---	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED	
	30 OVER	± ---	APPROVED BY M. ENOMOTO	DATE '92/8/4	DOCUMENT NO. SD-53268-011	SHEET NO. 2 OF 2
ANGULAR ± --- °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						

CONFIDENTIAL

注記 NOTES

- 1. 梱包数量： 1000 個/リール NUMBER OF CONNECTORS: 1000PCS/REEL
- 2. リードテープ長さ LEAD TAPE LENGTH

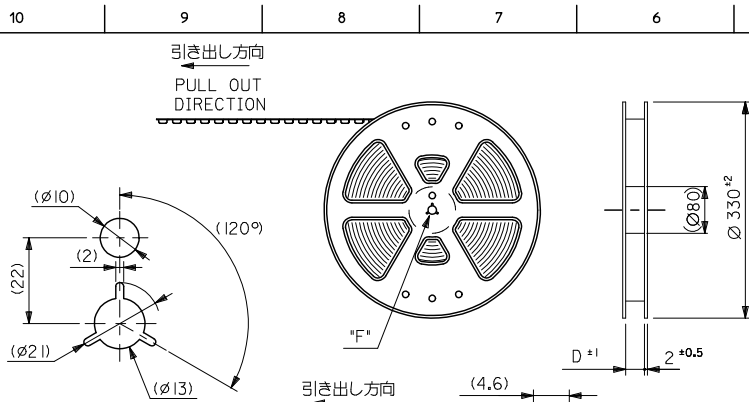
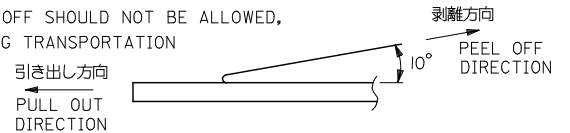
トップテープ TOP TAPE
 リーダー部 LEADER PART
 未接着部 NON-BONDED PART



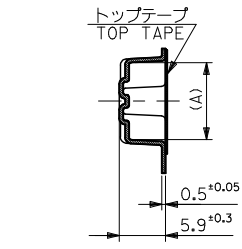
- 3. トップテープの剥離強度： (剥離方向は下図参照)

60gf MAX. 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)

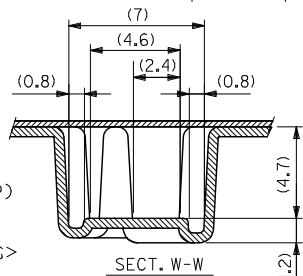
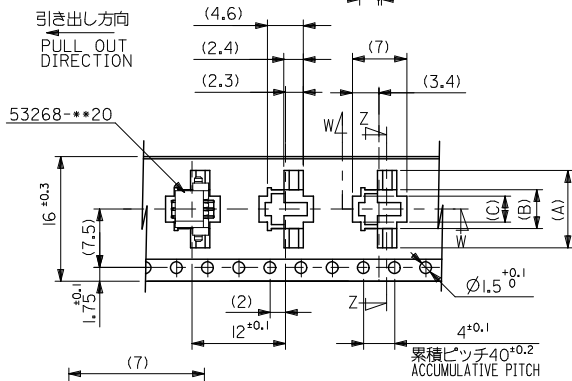
PEELING OFF FORCE OF TOP TAPE
 60gf MAX. (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION



DETAIL "F"



SECT. Z-Z



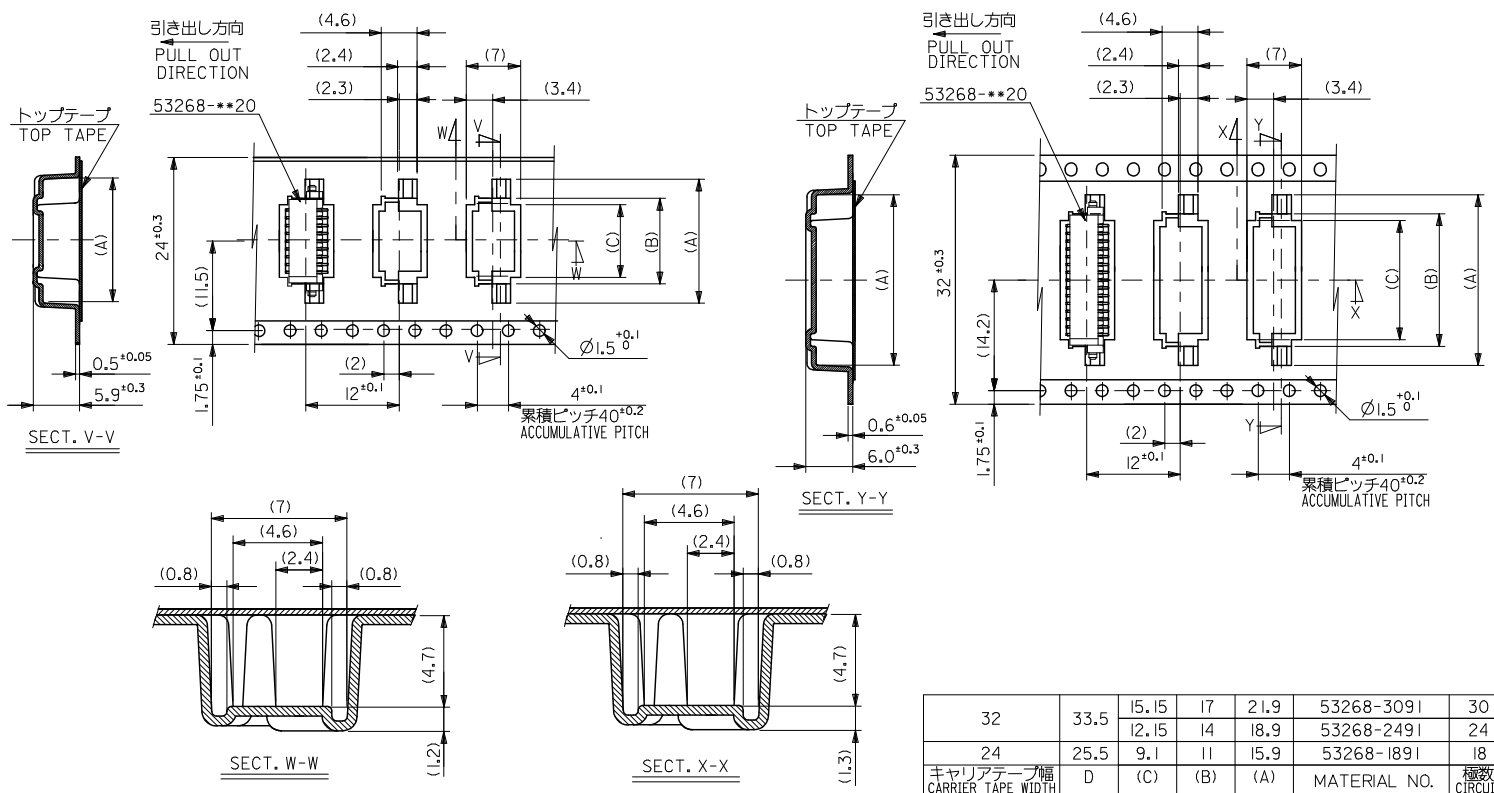
SECT. W-W

4. 材料
 キャリアテープ: ポリプロピレン (PP)
 トップテープ: PET, PE, PEF
 リール: ポлистиレン (PS)
 <リサイクル材を含む>
- MATERIAL
 CARRIER TAPE: POLYPROPYLENE
 TOP TAPE: PET, PE, PEF
 REEL: POLYSTYRENE (PS)
 <RECYCLE MATERIAL
 CONTAINED>

16	17.5	3.1	5	9.9	53268-0691	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極致 CIRCUIT
					MODEL NO.	53268-**91

REVISED EEC NO: J2009-0666 08/09/25 DRINKAKURAA 2008/09/25 CHYKOT HARUYAMA 2008/09/25 APPR: NIKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (1/2)		
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	DOCUMENT NO. SD-53268-012		
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2	
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



32	33.5	15.15	17	21.9	53268-3091	30
24	25.5	12.15	14	18.9	53268-2491	24
キャリアテープ幅 CARRIER TAPE WIDTH	D	9.1	11	15.9	53268-1891	18
					MATERIAL NO.	極致 CIRCUIT

MODEL NO. 53268-**91

REVISED EC NO: J2009-0666 DRAWN: KANAKURA 2008/09/25 CHKD: HARUYAMA 2008/09/25 APPR: NIKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (2/2)		
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	DOCUMENT NO. SD-53268-012		
	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2	